

**PI3B3125/PI3B3126**

**3.3V, 4-Bit, 2-Port Nanoswitchw/Individual Enables**

**Description**

The DIODES PI3B series of logic circuits are produced using the Company's advanced sub micron CMOS technology, achieving industry leading speed grades.

The PI3B3125 and PI3B3126 are 3.3 Volt, 4-bit bus switches designed with four individual 5Ω bus switches with fast individual enables in an industry standard 74XX125/126 pinout. When enabled via the associated Bus Enable ( $\overline{BE}$ ) pin, the "A" pin is directly connected to the "B" pin for that particular gate. The bus switch introduces no additional propagation delay or additional ground bounce noise.

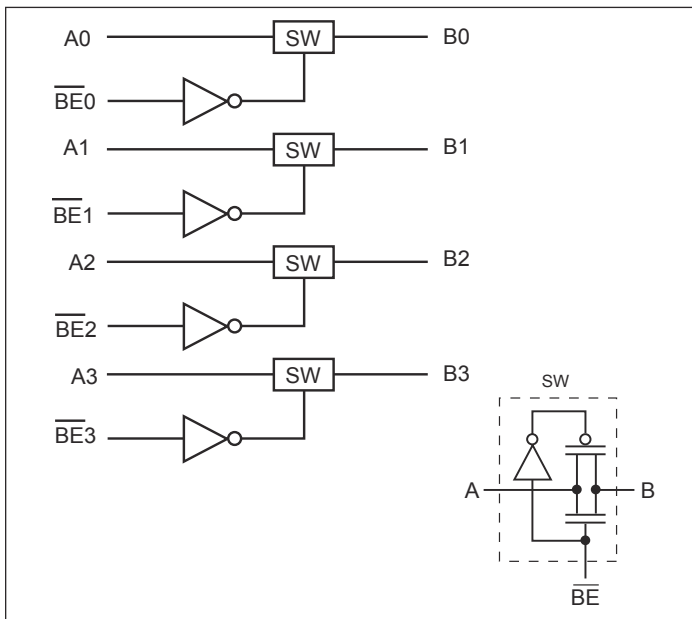
The PI3B3125 device has active LOW enables, and the PI3B3126 has active HIGH enables.

**Features**

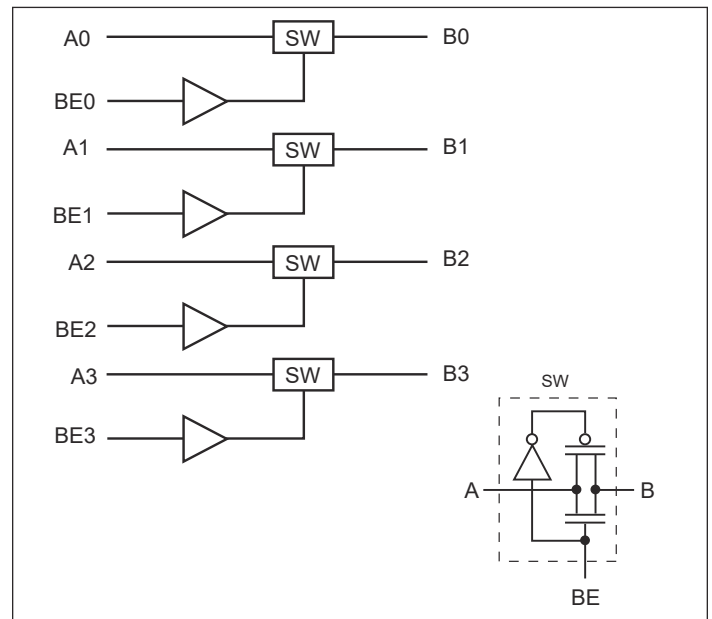
- Near zero propagation delay
- 5 Ohm switches connect inputs to outputs
- Fast Switching Speed - 4ns max.
- Ultra Low Quiescent Power (0.1μA Typical)
  - Ideally suited for notebook applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](https://www.diodes.com/quality/product-definitions/) or your local Diodes representative.
  - <https://www.diodes.com/quality/product-definitions/>
- Packaging (Pb-free & Green available):
  - 14-pin, SOIC (W), PI3B3125 only
  - 14-pin, TSSOP (L)
  - 16-pin, QSOP (Q)

**Logic Block Diagram**

**PI3B3125**



**PI3B3126**

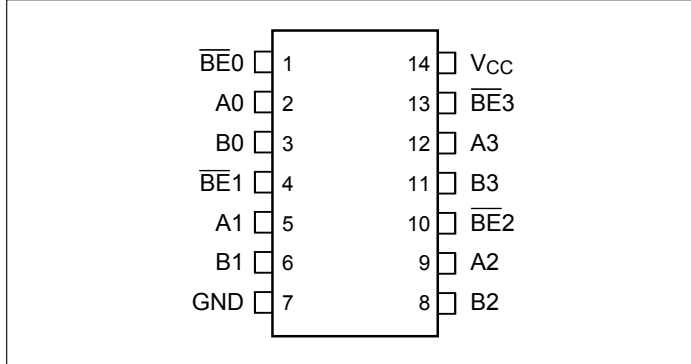


**Notes:**

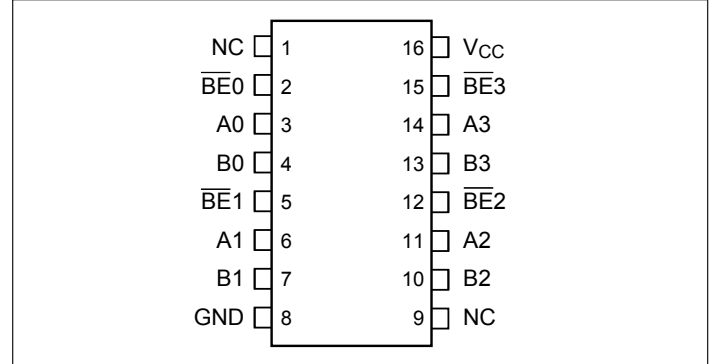
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Pin Configuration

### PI3B3125

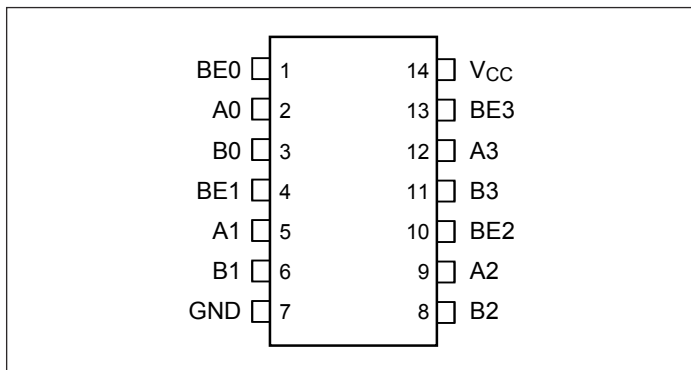


14-Pin, SOIC and TSSOP

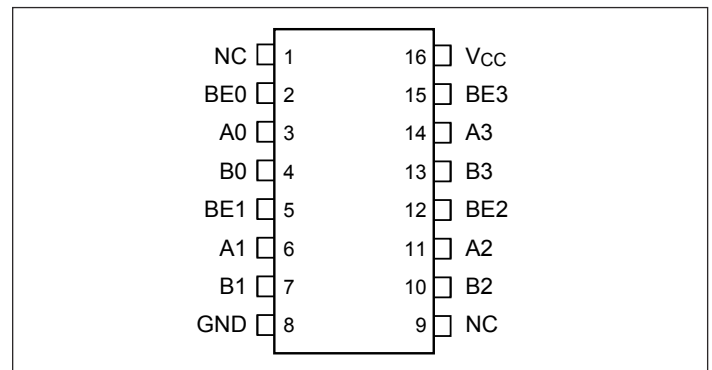


16-Pin, QSOP

### PI3B3126



14-Pin, TSSOP



16-Pin, QSOP

## Pin Description

Pin Name	Description
$\overline{\text{BE}}_n$	Switch Enable (PI3B3125)
$\text{BE}_n$	Switch Enable (PI3B3126)
A3-A0	Bus A
B3-B0	Bus B
$V_{CC}$	Power
GND	Ground

## Truth Table<sup>(1)</sup>

PI3B3125 $\overline{\text{BE}}_n$	PI3B3126 $\text{BE}_n$	$A_n$	$B_n$	$V_{CC}$	Function
X <sup>(2)</sup>	X	Hi-Z	Hi-Z	GND	Disconnect
H	L	Hi-Z	Hi-Z	$V_{CC}$	Disconnect
L	H	$B_n$	$A_n$	$V_{CC}$	Connect

### Notes:

- H = High Voltage Level, L = Low Voltage Level  
HI-Z = High Impedance, X = Don't Care
- A pull-up resistor should be provided for power-up protection.

## Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature.....	-65°C to +150°C
Supply Voltage to Ground Potential.....	-0.5V to +4.6V
DC Input Voltage.....	-0.5V to +4.6V
DC Output Current.....	120mA
Power Dissipation.....	0.5W
Junction Temperature (Tj).....	Max. 125°C

**Note:**

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## DC Electrical Characteristics

Over the Operating Range, T<sub>A</sub> = -40°C to +85°C, V<sub>CC</sub> = 3.3V ±10%

Parameter	Description	Test Conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Units
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed Logic HIGH Level	2.0			V
V <sub>IL</sub>	Input LOW Voltage	Guaranteed Logic LOW Level	-0.5		0.8	V
I <sub>IH</sub>	Input HIGH Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = V <sub>CC</sub>			±1	μA
I <sub>IL</sub>	Input LOW Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = GND			±1	μA
I <sub>OFF</sub>	Off Current	V <sub>CC</sub> = 0, V <sub>OUT</sub> = 3 to 3.6V			10	μA
V <sub>IK</sub>	Clamp Diode Voltage	V <sub>CC</sub> = Min., I <sub>IN</sub> = -18mA			-1.2	V
R <sub>ON</sub>	Switch On Resistance <sup>(3)</sup>	V <sub>CC</sub> = Min., V <sub>IN</sub> = 0.0V, I <sub>ON</sub> = 48mA or 60mA		5	8	Ω
		V <sub>CC</sub> = Min., V <sub>IN</sub> = 2.4V, I <sub>ON</sub> = 15mA		10	17	

**Notes:**

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = 25°C ambient and maximum loading.
- Measured by the voltage drop between A and B pin at indicated current through the switch. ON resistance is determined by the lower of the voltages on the two (A, B) pins.

## Capacitance

T<sub>A</sub> = 25°C, f = 1 MHz

Parameter <sup>(1)</sup>	Description	Test Conditions	Min.	Typ.	Max.	Units
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V		3.5		pF
C <sub>OFF</sub>	A/B Capacitance, Switch Off	V <sub>IN</sub> = 0V		8		pF

**Note:**

- This parameter is determined by device characterization but is not production tested.

## Power Supply Characteristics

Parameter	Description	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Units
$I_{CC}$	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$	$V_{IN} = \text{GND or } V_{CC}$		0.1	3	$\mu\text{A}$
$\Delta I_{CC}$	Supply Current per Input HIGH	$V_{CC} = \text{Max.}$	$V_{IN} = 3.0\text{V}^{(3)}$			750	$\mu\text{A}$

**Notes:**

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device.
- Typical values are at  $V_{CC} = 3.3\text{V}$ ,  $+25^\circ\text{C}$  ambient.
- Per driven input (control inputs only); A and B pins do not contribute to  $I_{CC}$ .

## Switching Characteristics over Operating Range

Parameter	Description	Conditions <sup>(1)</sup>	PI3B3125		Units
			Com.		
			Min.	Max.	
$t_{PLH}$ $t_{PHL}$	Propagation Delay <sup>(2,3)</sup> Ax to Bx, Bx to Ax	$C_L = 50\text{pF}$ $R_L = 500\Omega$		0.25	ns
$t_{PZH}$ $t_{PZL}$	Bus Enable Time	$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.0	3.0	ns
$t_{PHZ}$ $t_{PLZ}$	Bus Disable Time	$R_L = 500\Omega$	1.0	4.0	ns

Parameter	Description	Conditions <sup>(1)</sup>	PI3B3126		Units
			Com.		
			Min.	Max.	
$t_{PLH}$ $t_{PHL}$	Propagation Delay <sup>(2,3)</sup> Ax to Bx, Bx to Ax	$C_L = 50\text{pF}$ $R_L = 500\Omega$		0.25	ns
$t_{PZH}$ $t_{PZL}$	Bus Enable Time	$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.0	2.5	ns
$t_{PHZ}$ $t_{PLZ}$	Bus Disable Time	$R_L = 500\Omega$	1.0	4.0	ns

**Notes:**

- See test circuit and waveforms.
- This parameter is guaranteed but not tested on Propagation Delays.
- The bus switch contributes no propagational delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for 50pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

## Applications Information

### Logic Inputs

The logic control inputs can be driven up to +3.6V regardless of the supply voltage. For example, given a + 3.3V supply, IN may be driven low to 0V and high to 3.6V. Driving IN Rail-to-Rail® minimizes power consumption.

### Power-Supply Sequencing and Hot-Plug Information

Proper power-supply sequencing is recommended for all CMOS devices. Always apply V<sub>CC</sub> and GND before applying signals to input/output or control pins.

*Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd.*

## Part Marking

### PI3B3125

L Package	Q Package	W Package
YY: Year WW: Workweek 1st X: Assembly Site Code 2nd X: Fab Site Code	YY: Year WW: Workweek 1st G: Assembly Site Code 2nd G: Wafer Fab Site Code	YY: Year WW: Workweek 1st X: Assembly Site Code 2nd X: Wafer Fab Site Code

### PI3B3126

L Package	Q Package
1st Y: Die Rev 2nd Y: Year W: Workweek 1st X: Assembly Code 2nd X: Fab Code	Y: Year W: Workweek 1st X: Assembly Site Code 2nd X: Fab Site Code

**Packaging Mechanical**

**14-TSSOP (L)**

SYMBOLS	MIN.	NOM.	MAX.
A	–	–	1.20
A1	0.05	–	0.15
A2	0.80	1.00	1.05
b	0.19	–	0.30
c	0.09	–	0.20
D	4.90	5.00	5.10
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	–	–
$\theta$	0°	–	8°

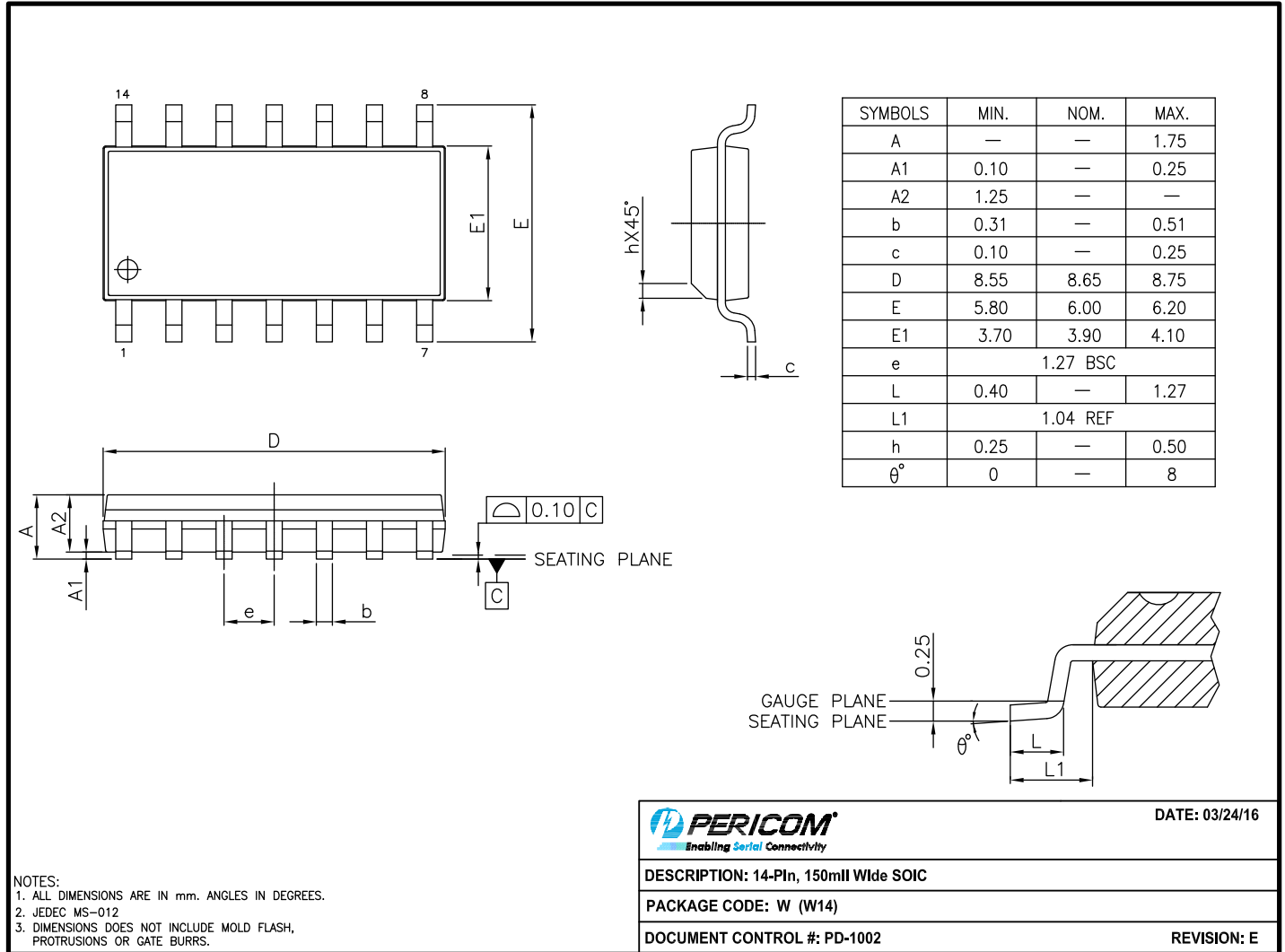
**NOTES:**  
 1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.  
 2. JEDEC MO-153F  
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

		DATE: 03/24/16
DESCRIPTION: 14-Pin, 173mil Wide TSSOP		
PACKAGE CODE: L (L14)		
DOCUMENT CONTROL #: PD-1309	REVISION: E	

16-0060

PI3B3125/PI3B3126

14-SOIC (W)



NOTES:  
 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.  
 2. JEDEC MS-012  
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

16-0055

<b>PERICOM</b> Enabling Serial Connectivity	DATE: 03/24/16
DESCRIPTION: 14-Pin, 150mil Wide SOIC	
PACKAGE CODE: W (W14)	
DOCUMENT CONTROL #: PD-1002	REVISION: E

16-QSOP (Q)

SYMBOLS	MIN.	NOM.	MAX.
A	—	—	0.069
A1	0.004	—	0.0098
A2	0.049	—	—
b	0.008	—	0.012
c	0.004	—	0.010
D	0.189	0.193	0.197
E1	0.150	0.154	0.158
E	0.228	0.236	0.244
L	0.016	—	0.050
L1	0.041 REF.		
e	0.025 BSC.		
$\theta^\circ$	0	—	8

UNIT : INCH

**NOTES:**  
 1. ALL DIMENSIONS IN INCH. ANGLES IN DEGREES.  
 2. JEDEC MO-137E  
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

		DATE: 04/08/16
DESCRIPTION: 16-Pin, 150mil Wide QSOP		
PACKAGE CODE: Q (Q16)		
DOCUMENT CONTROL #: PD-1201	REVISION: H	

16-0056

**For latest package info.**

please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>

**Ordering Information**

Ordering Code	Package Code	Package Description
PI3B3125LEX	L	14-Pin, 173mil Wide (TSSOP)
PI3B3125WEX	W	14-Pin, 150mil Wide (SOIC)
PI3B3125QEX	Q	16-Pin, 150mil Wide(QSOP)
PI3B3126LEX	L	14-Pin, 173mil Wide (TSSOP)
PI3B3126QEX	Q	16-Pin, 150mil Wide(QSOP)

**Notes:**

- No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
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- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- E = Pb-free and Green
- X suffix = Tape/Reel



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